

ATTY DKT. No.: U.S. SERIAL No.: FILED:

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AMAT/7532/CPI/UB/PJS
UNKNOWN
HEREWITH
APPLIED MATERIALS
ENHANCEMENT OF CU LINE RELIABILITY USING THIN ALD
TAN FILM TO CAP THE CU LINE
LING CHEN, ET AL.

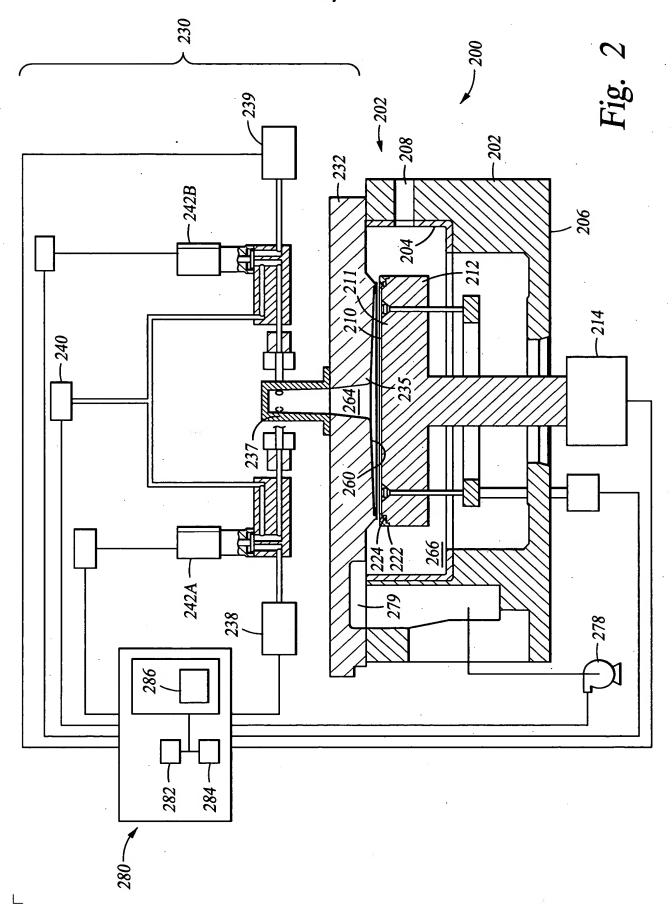
2. EV/354/7105111S

PAGE 2 OF 5 APPLICANT: TITLE:

INVENTOR:

EXPRESS MAIL No.: EV335471051US

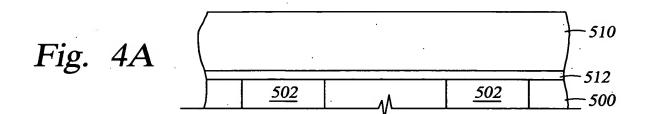
PAGE 2 OF 5

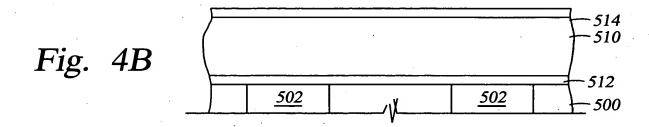


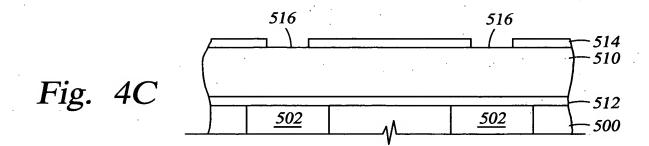
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ENHANCEMENT OF CU LINE RELIABILITY USING THIN ALD
TAN FILM TO CAP THE CU LINE APPLICANT: TITLE:

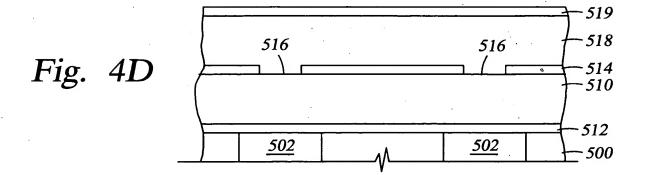
INVENTOR: LING CHEN, ET AL. EXPRESS MAIL No.: EV335471051US

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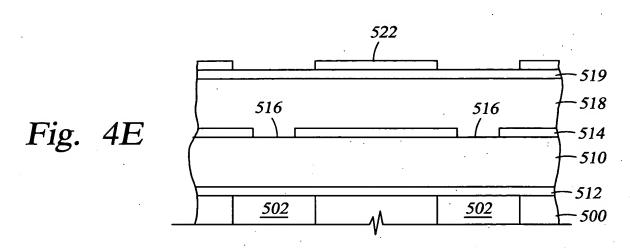
APPLICANT: APPLIED MATERIALS
TITLE: ENHANCEMENT OF CU LINE RELIABILITY USING THIN ALD

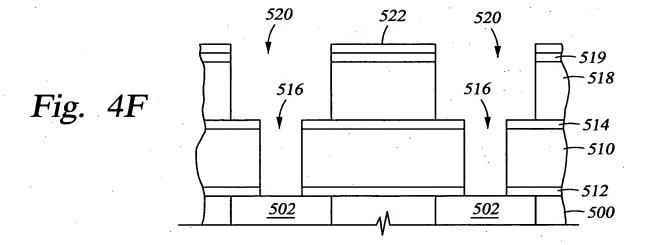
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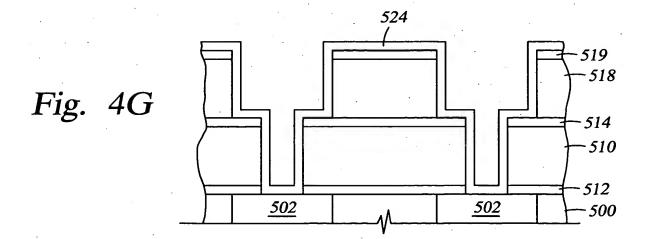
INVENTOR: LING CHEN, ET AL.

EXPRESS MAIL No.: EV335471051US

PAGE 4 OF 5







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APPLICANT:

APPLIED MATERIALS ENHANCEMENT OF CU LINE RELIABILITY USING THIN ALD TITLE:

TAN FILM TO CAP THE CU LINE LING CHEN, ET AL.

INVENTOR: LING CHEN, ET AL EXPRESS MAIL NO.: EV335471051US PAGE 5 OF 5

